MSB307H

GLASS PASSIVATED SINGLE-PHASE SURFACE MOUNT BRIDGE RECTIFIER

REVERSE VOLTAGE: **1000 VOLTS**
FORWARD CURRENT: **3 AMPERE**

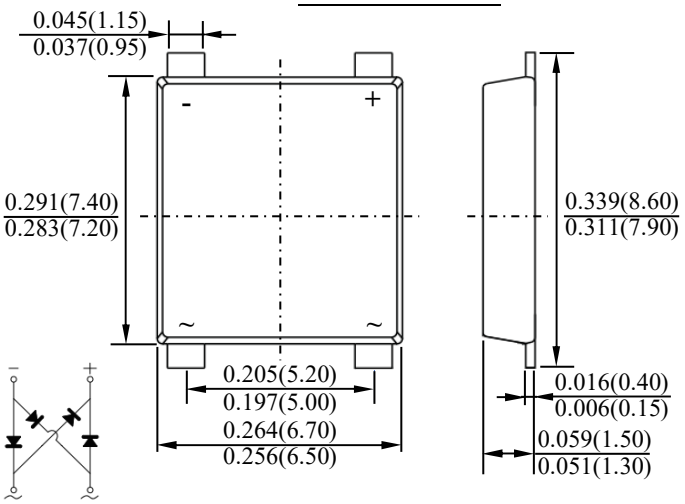
FEATURES

· Glass Passivated Junction Chip
· Low Reverse Leakage
· High Forward Surge Current Capability
· Suffix "H" indicates Halogen-free parts, ex. MSB307H

MECHANICAL DATA

Case : Molded plastic, MSBL
Epoxy : UL 94V-O rate flame retardant
Terminals : Leads solderable per MIL-STD-202,
method 208 guaranteed
Mounting position : Any

MSBL



Dimensions in inchs and (millimeters)

Maximum Ratings and Electrical Characteristics

Ratings at 25℃ ambient temperature unless otherwise specified.
Single phase, half wave, 60H_Z, resistive or inductive load.
For capacitive load, derate current by 20%.

Parameter	Symbols	*MSB307H*	Units
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	1000	**Volts**
Maximum RMS Voltage	V_{RMS}	700	**Volts**
Maximum DC Blocking Voltage	V_{DC}	1000	**Volts**
Maximum Average Forward Rectified Current at T_L=100℃	$I_{(AV)}$	3.0	**Amp**
Peak Forward Surge Current, 8.3ms single half-sine-wave superimposed on rated load (JEDEC method)	I_{FSM}	100	**Amp**
Maximum Forward Voltage at 1.5A DC and 25℃	V_F	1.0	**Volts**
Maximum Reverse Current at T_J=25℃	I_R	5.0	**uAmp**
at Rated DC Blocking Voltage T_J=125℃		200	
Typical Junction Capacitance (Note 1)	C_J	23	**pF**
Typical Thermal Resistance (Note 2)	$R_{\theta JA}$	55.0	**℃/W**
Operating and Storage Temperature Range	T_J，Tstg	-55 to +150	**℃**

NOTES:

1. Measured at 1 MHZ and applied reverse voltage of 4.0 VDC.
2. Mounted on glass epoxy PC board with 4×1.5"×1.5" （3.81cm ×3.81cm）copper pad.

RATINGS AND CHARACTERISTIC CURVES

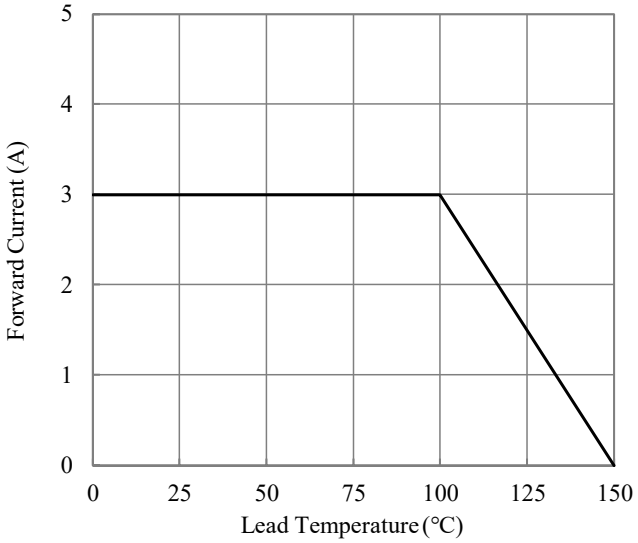


Fig. 1 Forward Current Derating Curve

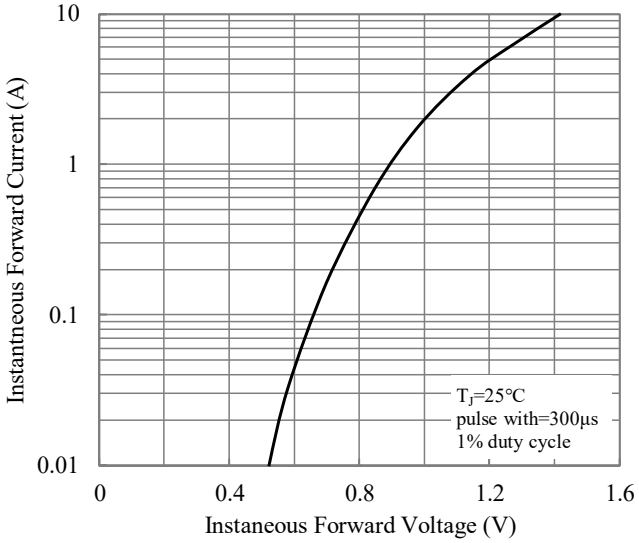


Fig. 2 Typical Instaneous Forward Characteristics

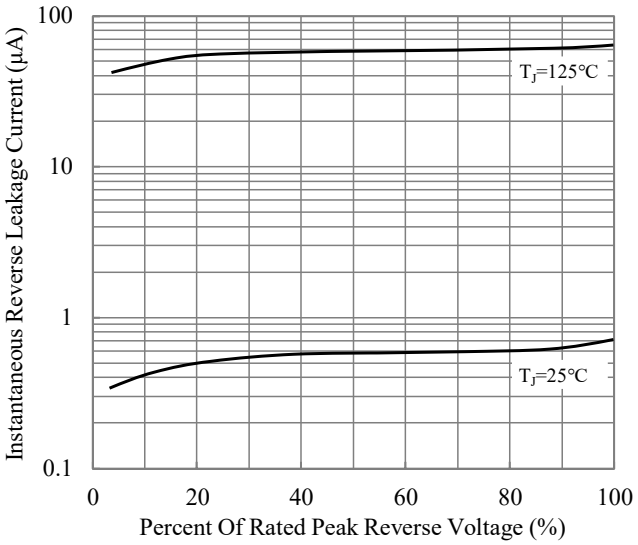


Fig. 3 Typical Reverse Leakage Characteristics

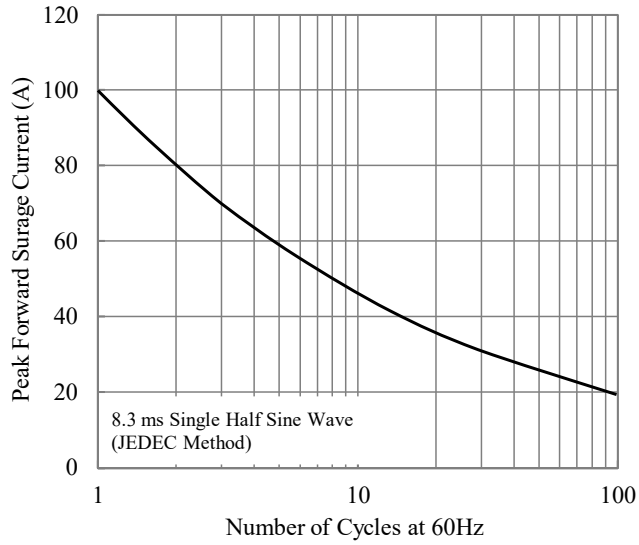


Fig. 4 Maximum Non-Repetitive Peak Forward Surage Current